Title (en)

INTERCONNECTS FOR WAFER-SCALE-INTEGRATED ASSEMBLY.

Title (de)

VERBINDUNGEN FÜR DEN ZUSAMMENBAU VON GESAMTSCHEIBEN INTEGRIERTER SCHALTUNGEN.

Title (fr)

INTERCONNEXION POUR UN ENSEMBLE INTEGRE A L'ECHELLE D'UNE TRANCHE.

Publication

EP 0253886 A1 19880127 (EN)

Application

EP 87902022 A 19861224

Priority

US 82062486 A 19860121

Abstract (en)

[origin: WO8704566A1] An assembly is obtained by stacking plural wafer-scale-integrated boards made of silicon. Connections between levels of the assembly are made by optical signals transmitted directly through the silicon boards.

Abstract (fr)

Un ensemble est obtenu en empilant plusieurs plaques en silicium intégrées à l'échelle d'une tranche. Des connexions entre des niveaux de l'ensemble sont réalisées par des signaux optiques transmis directement au travers des plaques de silicium.

IPC 1-7

H01L 31/16

IPC 8 full level

H01L 25/00 (2006.01); **G02B 6/43** (2006.01); **H01L 23/52** (2006.01); **H01L 25/065** (2006.01); **H01L 25/07** (2006.01); **H01L 25/18** (2006.01); **H01L 31/167** (2006.01)

CPC (source: EP KR)

G02B 6/43 (2013.01 - EP); **H01L 31/16** (2013.01 - KR); **H01L 31/167** (2013.01 - EP)

Citation (search report)

See references of WO 8704566A1

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DOCDB simple family (application)

US 8602805 W 19861224; EP 87902022 A 19861224; JP 50205187 A 19861224; KR 870700843 A 19870918